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Applicant:	Thomas J. Massingill, et al.
Confirmation No.:	6199
Serial No.:	09/997,589
Filed:	November 29, 2001
For:	*Multi-Chip Module and Method for Forming and Method for Deplating Defective Capacitors*
Art Group Unit:	1756
Examiner:	Thai, Luan C.
Atty. Dkt.:	6136-53804 (25916-162)

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Approved.
2/24/05
L.T.

LETTER TRANSMITTING FORMAL DRAWINGS TO THE OFFICIAL DRAFTSPERSON

Sir:

Transmitted herewith are formal drawings for the above-identified application bearing Figures 1 – 87 on thirty-four (34) drawing sheets.

July 23, 2004
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Respectfully submitted,

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